

Silicon Carbide Schottky Barrier Rectifier diode in bare die form

Rev 1.0 30/10/23

Features:

- Capable of high temperature operation >= 175°C
- High Frequency Operation
- High Surge Current Capability
- No Reverse Recovery / No Forward Recovery
- Positive Temperature Coefficient

Ordering Information:

The following part suffixes apply:

- No suffix MIL-STD-750 /2073 Visual Inspection
- "H" MIL-STD-750 /2073 Visual Inspection + MIL-PRF-38534 Class H LAT
- "K" MIL-STD-750 /2073 Visual Inspection + MIL-PRF-38534 Class K LAT

LAT = Lot Acceptance Test.

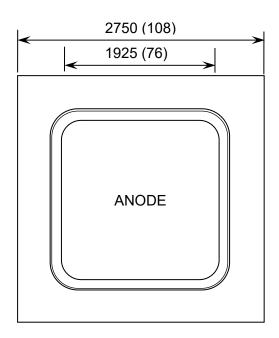
For further information on LAT process flows see below.

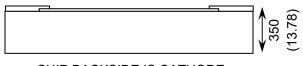
www.siliconsupplies.com\quality\bare-die-lot-qualification

Supply Formats:

- Default Die in Waffle Pack (400 per tray capacity)
- Sawn Wafer on Tape By specific request
- Unsawn Wafer By specific request
- With additional electrical selection By specific request

Die Dimensions in µm (mils)





CHIP BACKSIDE IS CATHODE

Mechanical Specification

Die Size (Unsawn)	2750 x 2750 108 x 108	µm mils	
Anode Pad Size	1925 x 1925 76 x 76	µm mils	
Die Thickness	350 (±20) 13.78 (0.79)	µm mils	
Top Metal Composition	Al 4µm		
Back Metal Composition	Ag 0.4µm		





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Absolute Maximum R	Ratings $T_J = 25^{\circ}C$ unless otherwise stated
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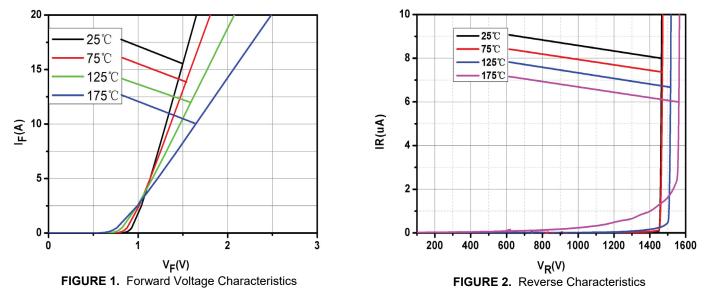
PARAMETER	SYMBOL	VALUE	UNIT
Repetitive peak reverse voltage	V _{RRM}	1200	V
Surge peak reverse voltage	V _{RSM}	1200	V
DC Peak Blocking Voltage	V _{BR}	1200	V
Average forward rectified current	I _{F(AV)}	15	А
Repetitive Peak Forward Surge Current	I _{FRM}	68	А
Peak Single-Cycle Non-Repetitive Surge Current	I _{FSM}	130	A
Operating Junction temperature	TJ	-55 to 175	C°
Storage Temperature Range	T _{STG}	-65 to 175	°C

Electrical Characteristics T_J = 25°C unless otherwise stated

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNIT
Maximum instantaneous forward voltage ¹	V _{F1}	V _{RRM} =1200V, I _{FM} = 15A	-	1.50	1.80	V
	V _{F2}	V _{RRM} = 1200V, I _{FM} = 15A, T _J = 175°C	-	2.20	3.00	
Maximum reverse leakage current ¹	I _{RM} @ V _{RM}	V _R = 1200V	-	3	40	μΑ
		V _R = 1200V, T _J = 175°C	-	10	50	
Junction Capacitance	CT	V _R = 0V, f = 1MHz,	-	990	-	pF
Reverse Recovery Charge	Qc	V _R = 800V , I _F = 15A, di/dt = 200A/µs	-	76.32	-	nC
Capacitance Stored Energy	Ec	V _R = 800V	-	39.24	-	μJ

1. Pulse Width≤ 300μ s, Duty Cycle ≤ 2.0%

Typical Characteristics $T_J = 25^{\circ}C$ unless otherwise stated







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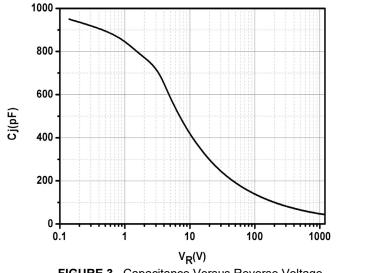


FIGURE 3. Capacitance Versus Reverse Voltage

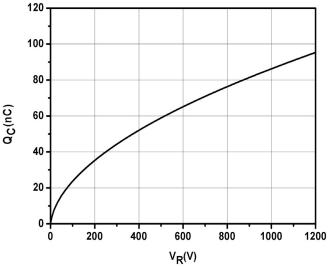


FIGURE 4. Total Capacitance Charge Versus Reverse Voltage

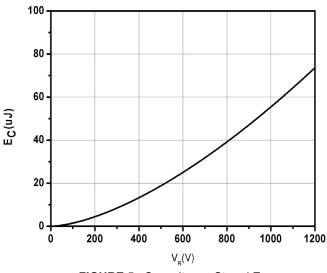


FIGURE 5. Capacitance Stored Energy

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